

1-Mbit (64 K x 16) Static RAM

Features

- Temperature ranges
 - Industrial: -40°C to 85°C
 - Automotive-A: -40°C to 85°C
- Pin-and function-compatible with CY7C1021CV33
- High speed
 - $t_{AA} = 10\text{ ns}$
- Low active power
 - $I_{CC} = 60\text{ mA}$ @ 10 ns
- Low CMOS standby power
 - $I_{SB2} = 3\text{ mA}$
- 2.0 V data retention
- Automatic power-down when deselected
- CMOS for optimum speed/power
- Independent control of upper and lower bits
- Available in Pb-free 44-pin 400-Mil wide molded SOJ, 44-pin TSOP II and 48-ball VFBGA packages

Functional Description^[1]

The CY7C1021DV33 is a high-performance CMOS static RAM organized as 65,536 words by 16 bits. This device has an automatic power-down feature that significantly reduces power consumption when deselected.

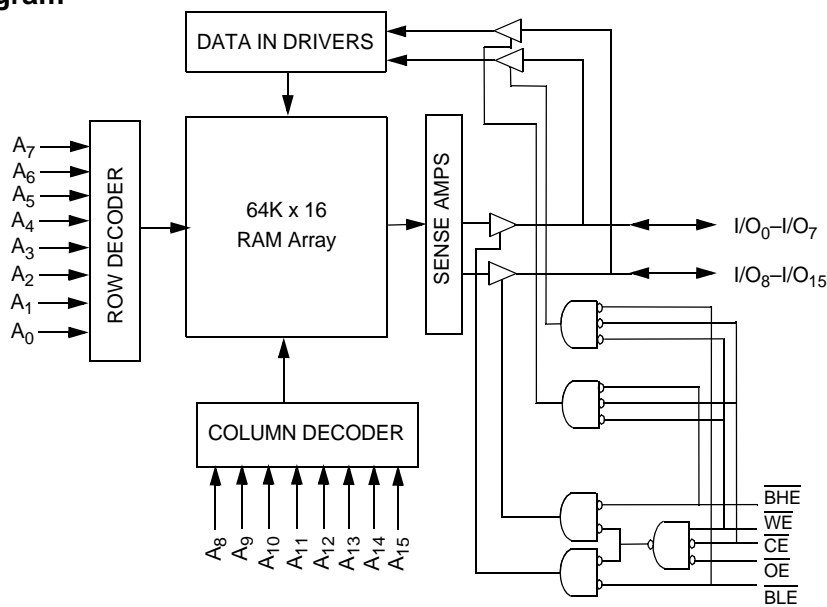
Writing to the device is accomplished by taking Chip Enable ($\overline{\text{CE}}$) and Write Enable ($\overline{\text{WE}}$) inputs LOW. If Byte Low Enable ($\overline{\text{BLE}}$) is LOW, then data from I/O pins (I/O_0 through I/O_7), is written into the location specified on the address pins (A_0 through A_{15}). If Byte High Enable ($\overline{\text{BHE}}$) is LOW, then data from I/O pins (I/O_8 through I/O_{15}) is written into the location specified on the address pins (A_0 through A_{15}).

Reading from the device is accomplished by taking Chip Enable ($\overline{\text{CE}}$) and Output Enable ($\overline{\text{OE}}$) LOW while forcing the Write Enable ($\overline{\text{WE}}$) HIGH. If Byte Low Enable ($\overline{\text{BLE}}$) is LOW, then data from the memory location specified by the address pins will appear on I/O_0 to I/O_7 . If Byte High Enable ($\overline{\text{BHE}}$) is LOW, then data from memory will appear on I/O_8 to I/O_{15} . See the truth table at the end of this data sheet for a complete description of Read and Write modes.

The input/output pins (I/O_0 through I/O_{15}) are placed in a high-impedance state when the device is deselected ($\overline{\text{CE}}$ HIGH), the outputs are disabled ($\overline{\text{OE}}$ HIGH), the $\overline{\text{BHE}}$ and $\overline{\text{BLE}}$ are disabled ($\overline{\text{BHE}}$, $\overline{\text{BLE}}$ HIGH), or during a Write operation ($\overline{\text{CE}}$ LOW, and $\overline{\text{WE}}$ LOW).

The CY7C1021DV33 is available in Pb-free 44-pin 400-Mil wide Molded SOJ, 44-pin TSOP II and 48-ball VFBGA packages.

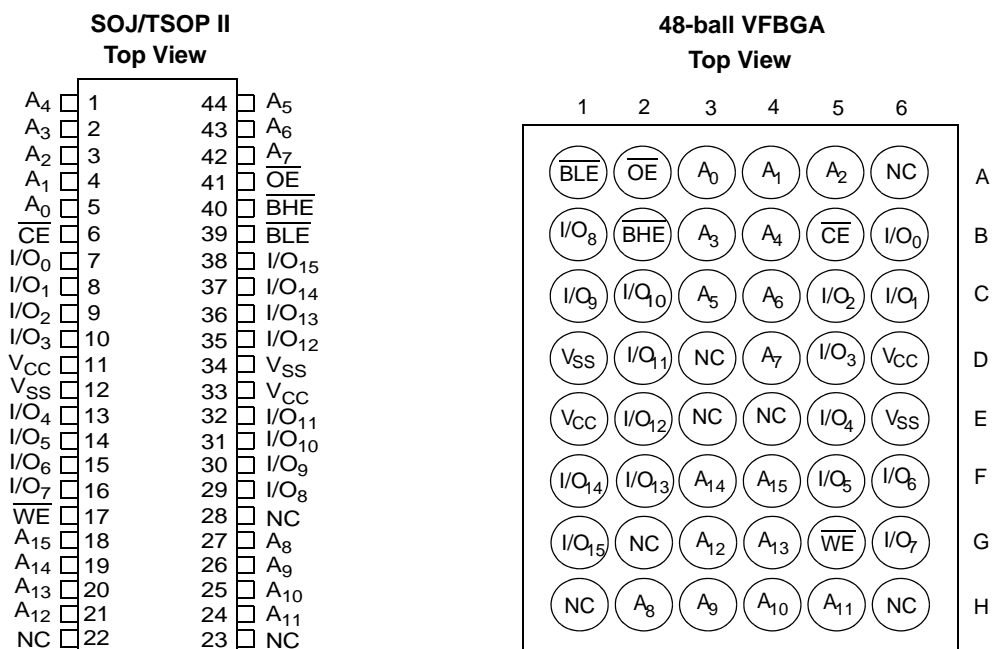
Logic Block Diagram



Selection Guide

	-10 (Industrial/Automotive-A)	Unit
Maximum access time	10	ns
Maximum operating current	60	mA
Maximum CMOS standby current	3	mA

Pin Configuration^[1]



Notes

1. NC pins are not connected on the die.

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage temperature -65 °C to +150 °C

Ambient temperature with power applied -55 °C to +125 °C

Supply voltage on V_{CC} to Relative GND^[2] ... -0.3 V to +4.6 V

DC Voltage applied to outputs in high-Z State^[2] -0.3 V to $V_{CC} + 0.3$ V

DC input voltage^[2] -0.3 V to $V_{CC} + 0.3$ V

Current into outputs (LOW) 20 mA

Static discharge voltage > 2001 V (per MIL-STD-883, method 3015)

Latch-up current >200 mA

Operating Range

Range	Ambient Temperature	V_{CC}	Speed
Industrial	-40 °C to +85°C	3.3 V \pm 0.3 V	10 ns
Automotive-A	-40 °C to +85°C		10 ns

DC Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	-10 (Ind'l/Auto-A)		Unit
			Min.	Max.	
V_{OH}	Output HIGH voltage	$V_{CC} = \text{Min.}, I_{OH} = -4.0 \text{ mA}$	2.4		V
V_{OL}	Output LOW voltage	$V_{CC} = \text{Min.}, I_{OL} = 8.0 \text{ mA}$		0.4	V
V_{IH}	Input HIGH voltage		2.0	$V_{CC} + 0.3$	V
V_{IL}	Input LOW voltage ^[2]		-0.3	0.8	V
I_{IX}	Input leakage current	$\text{GND} \leq V_I \leq V_{CC}$	-1	+1	μA
I_{OZ}	Output leakage current	$\text{GND} \leq V_I \leq V_{CC}$, Output Disabled	-1	+1	μA
I_{CC}	V_{CC} operating supply current	$V_{CC} = \text{Max.}, I_{OUT} = 0 \text{ mA}, f = f_{MAX} = 1/t_{RC}$	100 MHz	60	mA
			83 MHz	55	mA
			66 MHz	45	mA
			40 MHz	30	mA
I_{SB1}	Automatic CE Power-Down Current —TTL Inputs	Max. $V_{CC}, \overline{CE} \geq V_{IH}$ $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}, f = f_{MAX}$		10	mA
I_{SB2}	Automatic CE Power-Down Current —CMOS Inputs	Max. $V_{CC}, \overline{CE} \geq V_{CC} - 0.3 \text{ V},$ $V_{IN} \geq V_{CC} - 0.3 \text{ V}$ or $V_{IN} \leq 0.3 \text{ V}, f = 0$		3	mA

Capacitance^[3]

Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input capacitance	$T_A = 25^\circ\text{C}, f = 1 \text{ MHz}, V_{CC} = 3.3 \text{ V}$	8	pF
C_{OUT}	Output capacitance		8	pF

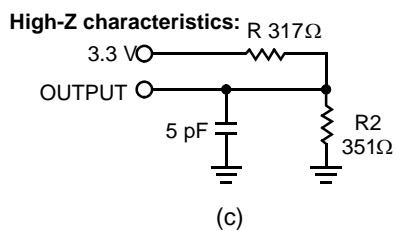
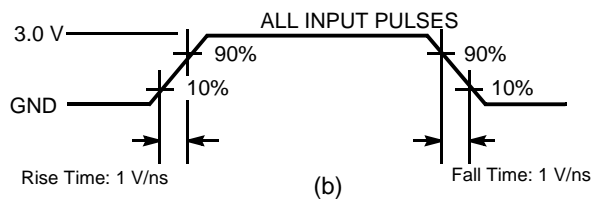
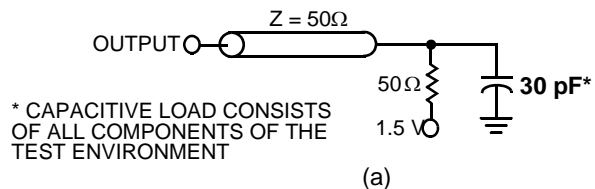
Thermal Resistance^[3]

Parameter	Description	Test Conditions	SOJ	TSOP II	VFBGA	Unit
Θ_{JA}	Thermal resistance (Junction to Ambient)	Still Air, soldered on a 3 x 4.5 inch, four-layer printed circuit board	59.52	53.91	36	°C/W
Θ_{JC}	Thermal resistance (Junction to Case)		36.75	21.24	9	°C/W

Notes

- $V_{IL}(\text{min.}) = -2.0 \text{ V}$ and $V_{IH}(\text{max.}) = V_{CC} + 1 \text{ V}$ for pulse durations of less than 5 ns.
- Tested initially and after any design or process changes that may affect these parameters.

AC Test Loads and Waveforms^[4]



Note

4. AC characteristics (except High-Z) are tested using the load conditions shown in Figure (a). High-Z characteristics are tested for all speeds using the test load shown in Figure (c).

Switching Characteristics Over the Operating Range^[5]

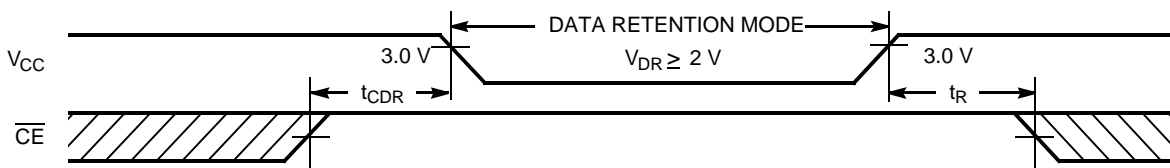
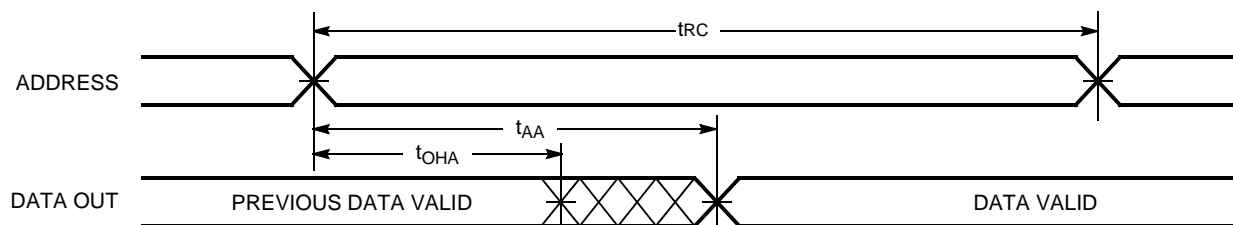
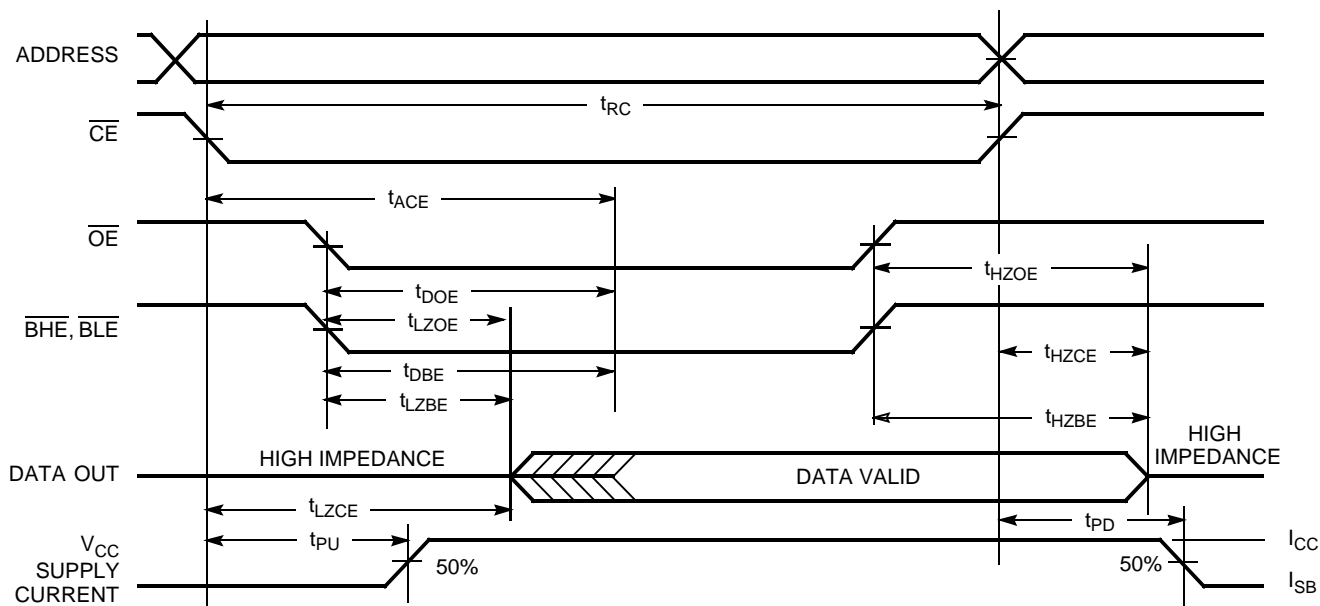
Parameter	Description	-10 (Ind'I/Auto-A)		Unit
		Min.	Max.	
Read Cycle				
t _{power} ^[6]	V _{CC} (typical) to the first access	100		μs
t _{RC}	Read cycle time	10		ns
t _{AA}	Address to data valid		10	ns
t _{OHA}	Data hold from address change	3		ns
t _{ACE}	$\overline{\text{CE}}$ LOW to data valid		10	ns
t _{DOE}	$\overline{\text{OE}}$ LOW to data valid		5	ns
t _{LZOE}	$\overline{\text{OE}}$ LOW to low-Z ^[8]	0		ns
t _{HZOE}	$\overline{\text{OE}}$ HIGH to high-Z ^[7, 8]		5	ns
t _{LZCE}	$\overline{\text{CE}}$ LOW to low-Z ^[8]	3		ns
t _{HZCE}	$\overline{\text{CE}}$ HIGH to high-Z ^[7, 8]		5	ns
t _{PU} ^[9]	$\overline{\text{CE}}$ LOW to power-up	0		ns
t _{PD} ^[9]	$\overline{\text{CE}}$ HIGH to power-down		10	ns
t _{DBE}	Byte Enable to data valid		5	ns
t _{LZBE}	Byte Enable to low-Z	0		ns
t _{HZBE}	Byte Disable to high-Z		6	ns
Write Cycle ^[10]				
t _{WC}	Write cycle time	10		ns
t _{SCE}	$\overline{\text{CE}}$ LOW to write end	8		ns
t _{AW}	Address set-up to write end	8		ns
t _{HA}	Address hold from write end	0		ns
t _{SA}	Address set-up to write start	0		ns
t _{PWE}	$\overline{\text{WE}}$ pulse width	7		ns
t _{SD}	Data set-up to write end	5		ns
t _{HD}	Data hold from write end	0		ns
t _{LZWE}	$\overline{\text{WE}}$ HIGH to low-Z ^[8]	3		ns
t _{HZWE}	$\overline{\text{WE}}$ LOW to high-Z ^[7, 8]		5	ns
t _{BW}	Byte enable to end of write	7		ns

Notes

- Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5 V, input pulse levels of 0 to 3.0 V.
- t_{POWER} gives the minimum amount of time that the power supply should be at typical V_{CC} values until the first memory access can be performed.
- t_{HZOE} , t_{HZBE} , t_{HZCE} , and t_{HZWE} are specified with a load capacitance of 5 pF as in (c) of AC Test Loads. Transition is measured when the outputs enter a high impedance state.
- At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , t_{HZOE} is less than t_{LZOE} , and t_{HZWE} is less than t_{LZWE} for any given device.
- This parameter is guaranteed by design and is not tested.
- The internal Write time of the memory is defined by the overlap of $\overline{\text{CE}}$ LOW, $\overline{\text{WE}}$ LOW and $\overline{\text{BHE/BL E}}$ LOW. $\overline{\text{CE}}$, $\overline{\text{WE}}$ and $\overline{\text{BHE/BL E}}$ must be LOW to initiate a Write and the transition of these signals can terminate the Write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the Write.

Data Retention Characteristics Over the Operating Range

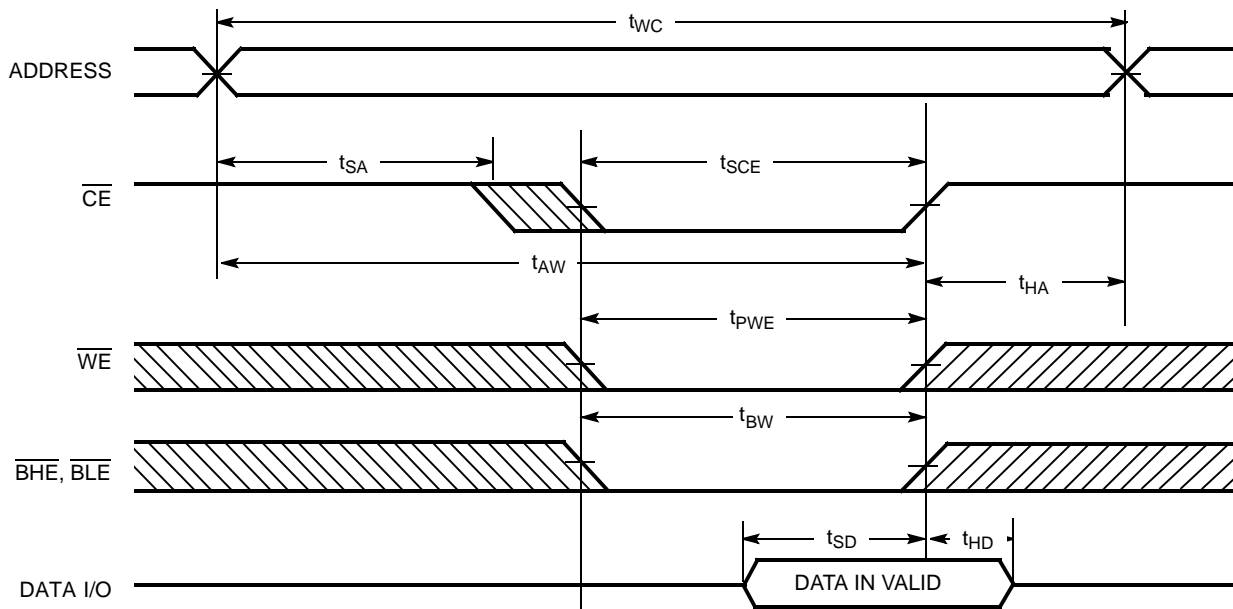
Parameter	Description	Conditions	Min.	Max.	Unit
V_{DR}	V_{CC} for data retention		2		V
I_{CCDR}	Data retention current	$V_{CC} = V_{DR} = 2.0\text{ V}$, $\overline{CE} \geq V_{CC} - 0.3\text{ V}$, $V_{IN} \geq V_{CC} - 0.3\text{ V}$ or $V_{IN} \leq 0.3\text{ V}$ Industrial		3	mA
$t_{CDR}^{[3]}$	Chip deselect to data retention time		0		ns
$t_R^{[11]}$	Operation recovery time		t_{RC}		ns

Data Retention Waveform

Switching Waveforms
Read Cycle No. 1 (Address Transition Controlled)^[12, 13]

Read Cycle No. 2 (\overline{OE} Controlled)^[13, 14]

Notes

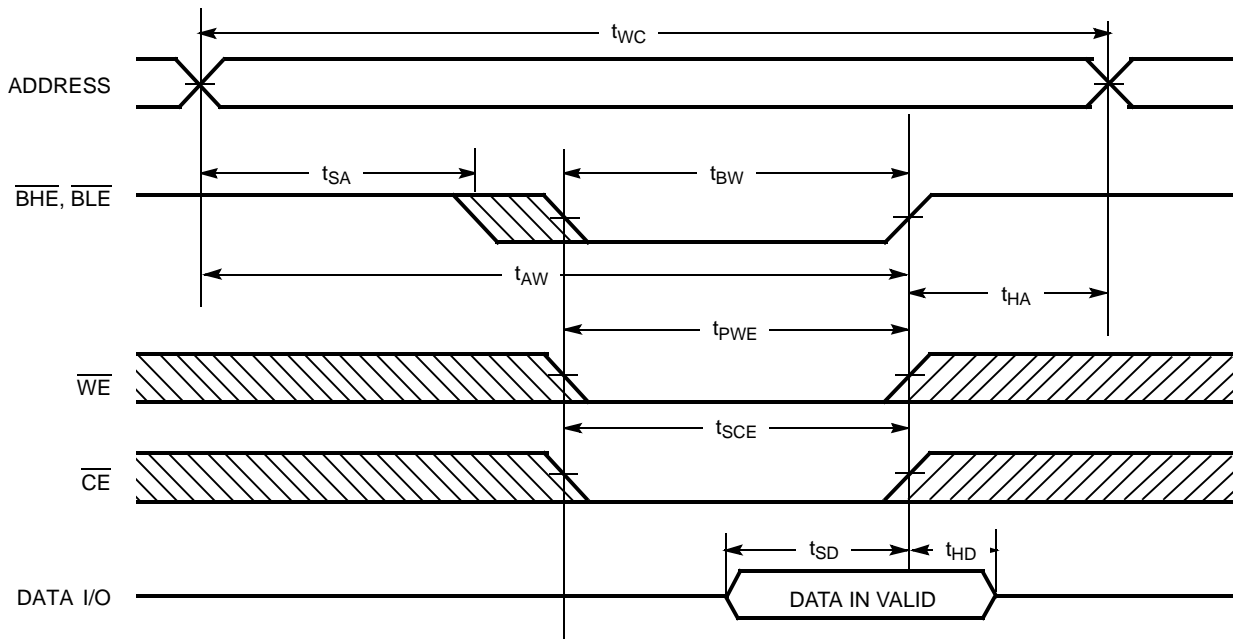
11. Full device operation requires linear V_{CC} ramp from V_{DR} to $V_{CC(min.)} \geq 50\text{ }\mu\text{s}$ or stable at $V_{CC(min.)} \geq 50\text{ }\mu\text{s}$.
12. Device is continuously selected. \overline{OE} , \overline{CE} , \overline{BHE} and/or $\overline{BLE} = V_{IL}$.
13. \overline{WE} is HIGH for Read cycle.
14. Address valid prior to or coincident with \overline{CE} transition LOW.

Switching Waveforms (continued)

Write Cycle No. 1 ($\overline{\text{CE}}$ Controlled)^[15, 16]



Write Cycle No. 2 ($\overline{\text{BLE}}$ or $\overline{\text{BHE}}$ Controlled)

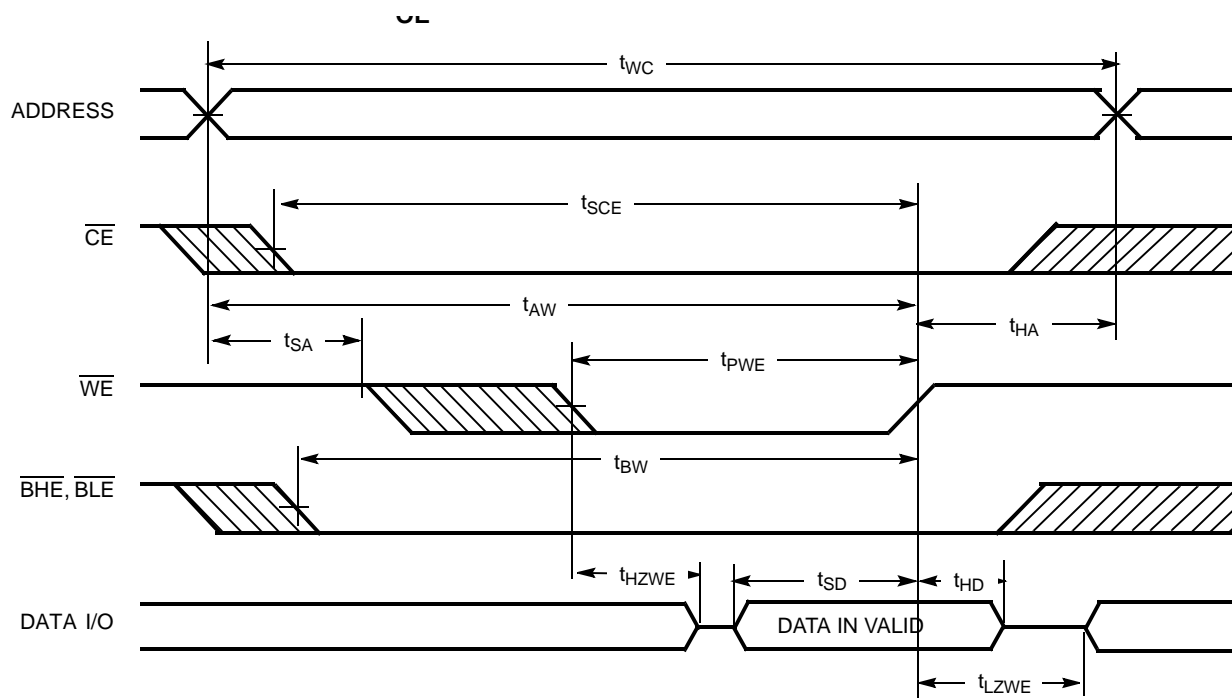


Notes

15. Data I/O is high impedance if $\overline{\text{OE}}$ or $\overline{\text{BHE}}$ and/or $\overline{\text{BLE}} = V_{\text{IH}}$.

16. If $\overline{\text{CE}}$ goes HIGH simultaneously with $\overline{\text{WE}}$ going HIGH, the output remains in a high-impedance state.

Switching Waveforms (continued)

Write Cycle No. 3 ($\overline{\text{WE}}$ Controlled, $\overline{\text{OE}}$ LOW)

Truth Table

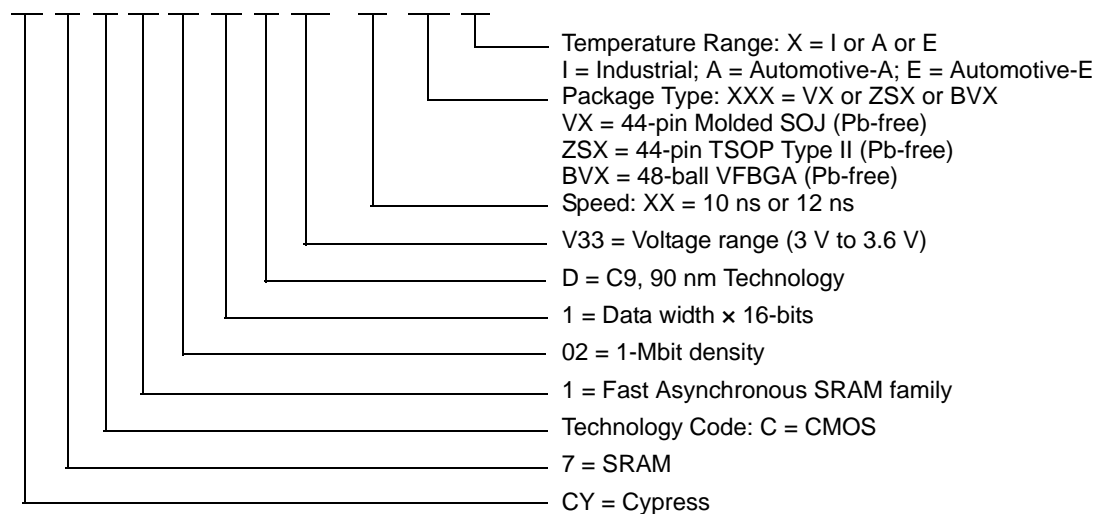
$\overline{\text{CE}}$	$\overline{\text{OE}}$	$\overline{\text{WE}}$	$\overline{\text{BLE}}$	$\overline{\text{BHE}}$	I/O ₀ –I/O ₇	I/O ₈ –I/O ₁₅	Mode	Power
H	X	X	X	X	High-Z	High-Z	Power-down	Standby (I_{SB})
L	L	H	L	L	Data Out	Data Out	Read – All bits	Active (I_{CC})
			L	H	Data Out	High-Z	Read – Lower bits only	Active (I_{CC})
			H	L	High-Z	Data Out	Read – Upper bits only	Active (I_{CC})
L	X	L	L	L	Data In	Data In	Write – All bits	Active (I_{CC})
			L	H	Data In	High-Z	Write – Lower bits only	Active (I_{CC})
			H	L	High-Z	Data In	Write – Upper bits only	Active (I_{CC})
L	H	H	X	X	High-Z	High-Z	Selected, outputs disabled	Active (I_{CC})
L	X	X	H	H	High-Z	High-Z	Selected, outputs disabled	Active (I_{CC})

Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C1021DV33-10VXI	51-85082	44-pin (400-Mil) Molded SOJ (Pb-free)	Industrial
	CY7C1021DV33-10ZSXI	51-85087	44-pin TSOP Type II (Pb-free)	
	CY7C1021DV33-10BVXI	51-85150	48-ball VFBGA (Pb-free)	
10	CY7C1021DV33-10ZSXA	51-85087	44-pin TSOP Type II (Pb-free)	Automotive-A

Ordering Code Definitions

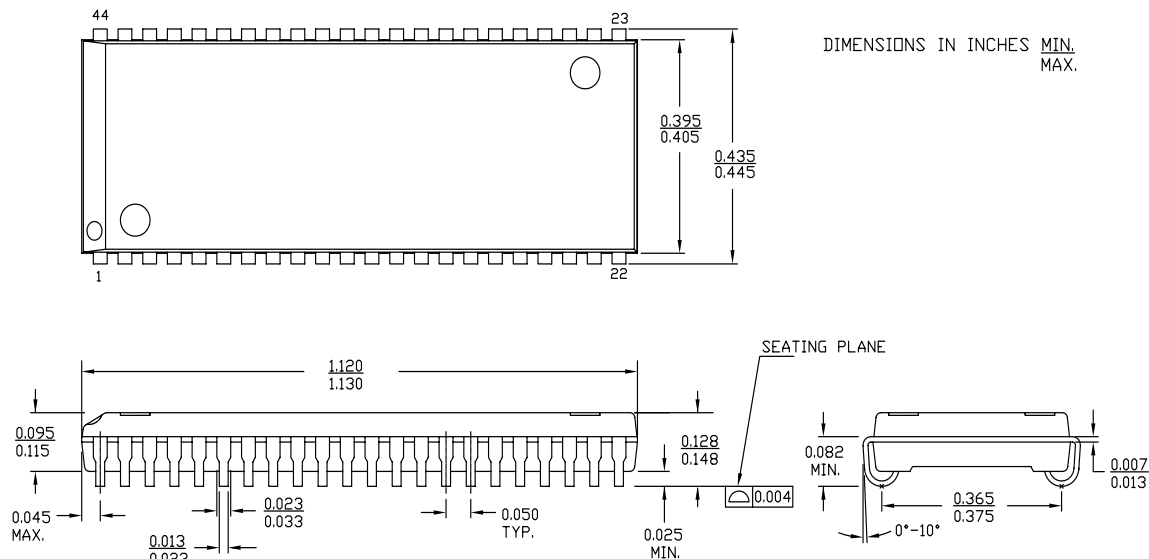
CY 7 C 1 02 1 D V33 - XX XXX X



Please contact your local Cypress sales representative for availability of these parts.

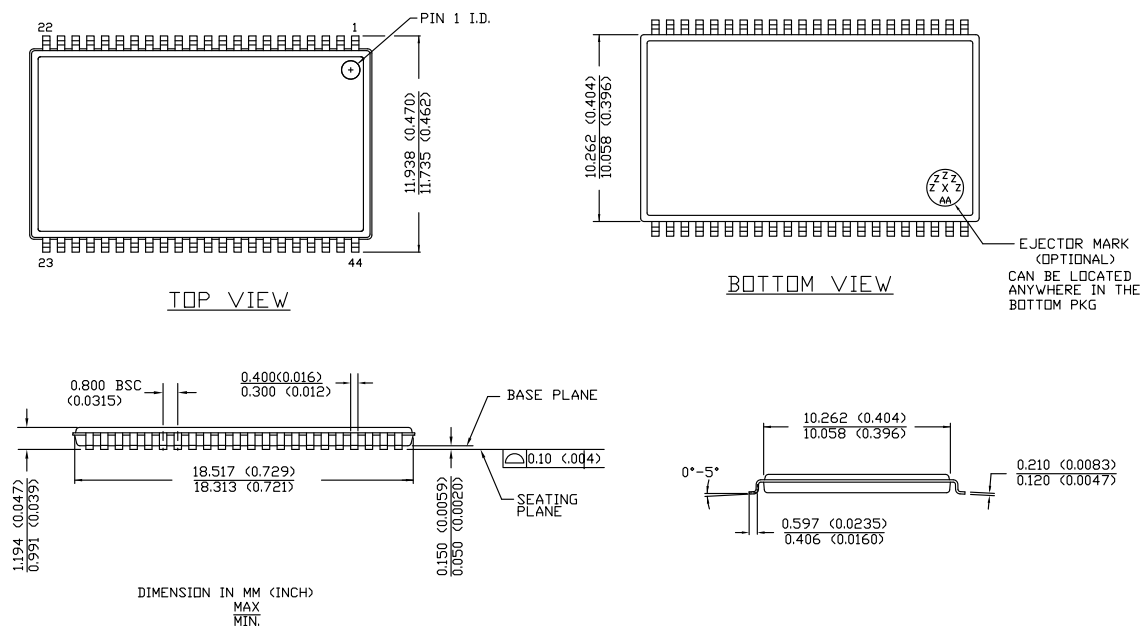
Package Diagrams

Figure 1. 44-pin (400-Mil) Molded SOJ (51-85082)



51-85082 *D

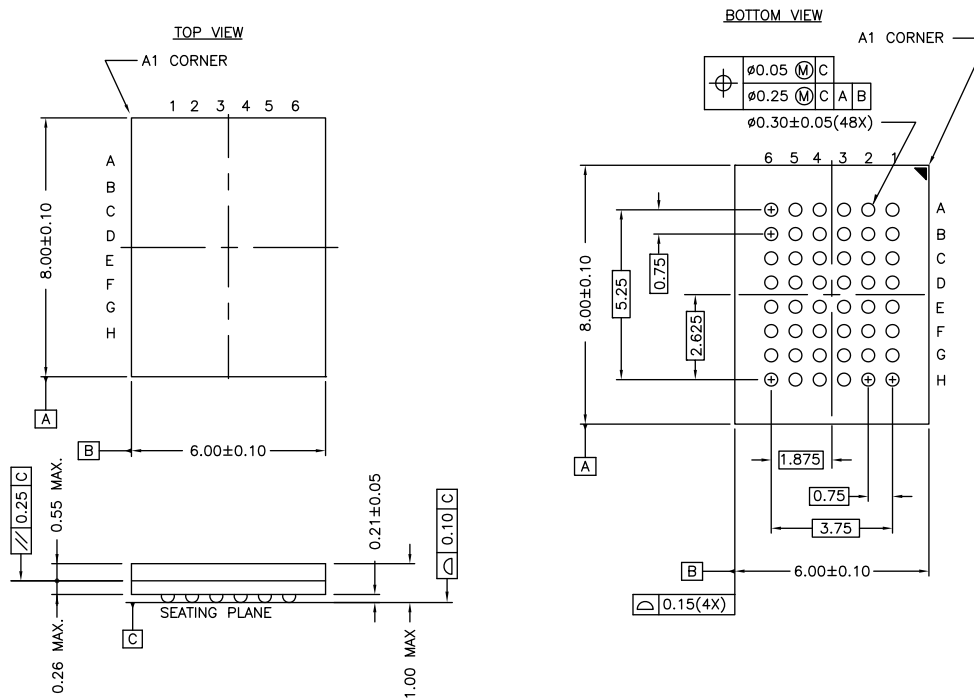
Figure 2. 44-pin Thin Small Outline Package Type II (51-85087)



51-85087 *D

Package Diagrams (continued)

Figure 3. 48-ball VFBGA (6 x 8 x 1 mm) (51-85150)



51-85150 *G

Document History Page

Document Title: CY7C1021DV33, 1-Mbit (64K x 16) Static RAM Document Number: 38-05460				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	201560	See ECN	SWI	Advance Information data sheet for C9 IPP
*A	233693	See ECN	RKF	DC parameters are modified as per Eros (Spec # 01-02165). Pb-free Offering In Ordering Information
*B	263769	See ECN	RKF	Changed I/O ₁ – I/O ₁₆ to I/O ₀ – I/O ₁₅ Added Data Retention Characteristics table Added T _{power} Spec in Switching Characteristics table Shaded Ordering Information
*C	307601	See ECN	RKF	Reduced Speed bins to –8 and –10 ns
*D	520652	See ECN	VKN	Converted from Preliminary to Final Removed Commercial Operating range Removed 8 ns speed bin Added I _{CC} values for the frequencies 83MHz, 66MHz and 40MHz Added Automotive Information Updated Thermal Resistance table Updated Ordering Information Table Changed Overshoot spec from V _{CC} +2 V to V _{CC} +1 V in footnote #4
*E	2898399	03/24/2010	AJU	Updated Package Diagrams
*F	3109897	12/14/2010	AJU	Added Ordering Code Definitions . Updated Package Diagrams .
*G	3421856	10/25/2011	TAVA	Template Update Updated Features, Selection Guide, Operating Range, DC Electrical Characteristics Over the Operating Range, Switching Characteristics Over the Operating Range^[5], Data Retention Characteristics Over the Operating Range, Switching Waveforms, and Ordering Information Updated Package Diagrams

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